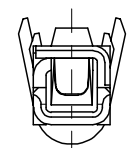
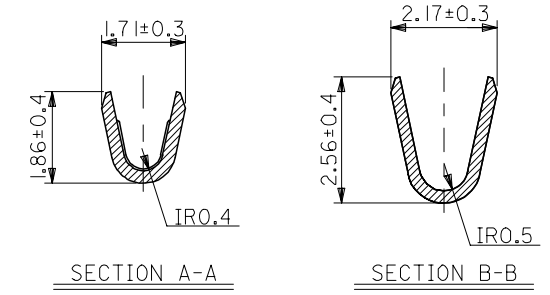


- 注)  
NOTES
1. 材質 : りん青銅 t0.25  
MATERIAL : PHOSPHOR BRONZE t0.25
  2. メッキ仕様  
PLATING  
接点部 : 金メッキ 0.3μmMIN.  
CONTACT AREA : GOLD 0.3μmMIN.  
圧着部 : 錫メッキ 1.0μmMIN.  
CRIMP AREA : TIN 1.0μmMIN.  
下地メッキ : ニッケルメッキ 2μmMIN.  
UNDER PLATING : NICKEL 2μmMIN.
  3. 適用圧着ハウジング : 51209-1001  
APPLICABLE CRIMP HOUSING : 51209-1001
  4. 適用電線範囲 : AWG #22 - #28  
APPLICABLE WIRES : AWG#22 - #28
  5. 被覆外径 : φ1.2mmMAX.  
INSULATION O.D : φ1.2 mmMAX.
  6. 適用圧着工具 (手動) : 57401-5300  
APPLICABLE CRIMP TOOL (HAND) : 57401-5300  
(半自動) : 57401-3000  
(SEMI-AUTOMATIC) : 57401-3000
  7. 適用引抜工具 : 57401-6000  
APPLICABLE EXTRACTION TOOL : 57401-6000
  8. 本製品は 59351-8\*87 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 59351-8\*87.



バラ状 LOOSE	59351-8128	59351-****
連鎖状 CHAIN	59351-8028	
端子形状 TERMINAL CONFIGURATION	MATERIAL NO.	MODEL NO.

RELEASED EC NO: J2007-0955 DRWN: NABE I 2006/10/02 CHKD: K. TOYODA 2006/10/05 APPR: NUKITA 2006/10/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NABE I	DATE '06/09/29	TITLE 2.0 I/O CRIMP TERMINAL		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE '06/09/29	-LEAD FREE-		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE '06/09/29	MOLEX MOLEX INCORPORATED		
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-59351-003		1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							